

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

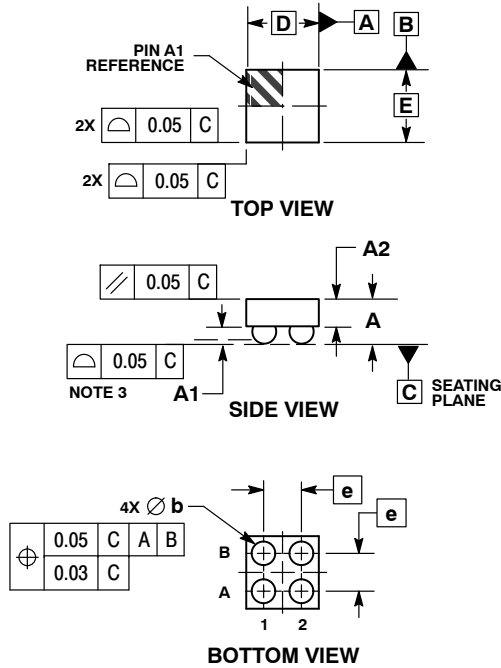
ON Semiconductor®



SCALE 4:1

WLCSP4, 0.76x0.76
CASE 567FJ
ISSUE O

DATE 17 APR 2012

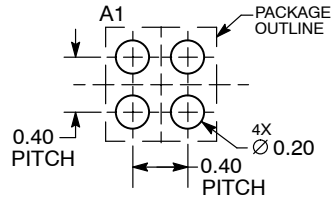


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.57 | 0.63 |
| A1 | 0.18 | 0.23 |
| A2 | 0.40 | REF |
| b | 0.24 | 0.28 |
| D | 0.76 | BSC |
| E | 0.76 | BSC |
| e | 0.40 | BSC |

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| DESCRIPTION: | WLCSP4, 0.76X0.76 | PAGE 1 OF 1 |

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